

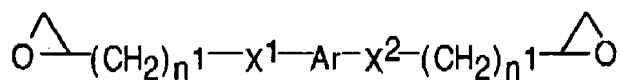
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JUN 08 2007

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Cancelled)
2. (Currently Amended) A composition comprising:
~~the compound of claim 1; and~~
a compound comprising:
at least one epoxy group;
at least one liquid crystalline disrupting moiety;
a melting point temperature of the compound that is less than 140°C; and
liquid crystallinity of the compound at a temperature greater than 150°C; and
a filler having a coefficient of thermal expansion that is closer to a coefficient of thermal expansion of silicon than to a coefficient of thermal expansion of an epoxy medium in which the filler is employed that is comparable to that of silicon.
3. (Withdrawn) A method comprising:
contacting a surface of a microelectronic device with the composition of claim 2; and
solidifying the composition on the surface.
4. (Withdrawn) A microelectronic device comprising:
a surface; and
a composition solidified on the surface by the method of claim 3.
5. (Currently Amended) The compound of claim ~~[[1]]~~ 2, having the formula:



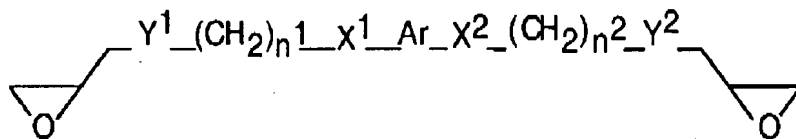
wherein

Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, and diphenyl 1,4-cyclohexane-dicarboxylate;

X¹ and X² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

6. (Currently Amended) The compound of claim [[1]]2, having the formula:



wherein

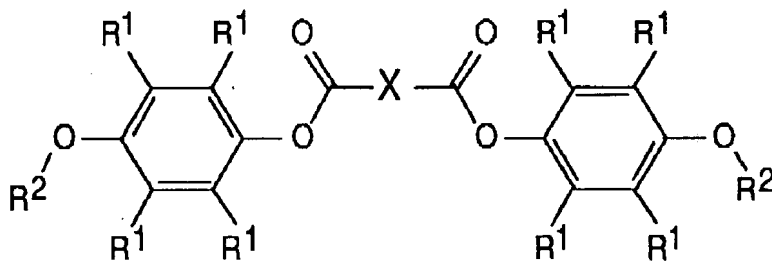
Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, diphenyl 1,4-cyclohexanedicarboxylate;

X¹ and X² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine;

Y¹ and Y² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

7. (Currently Amended) The compound of claim [[1]]2, having the formula:



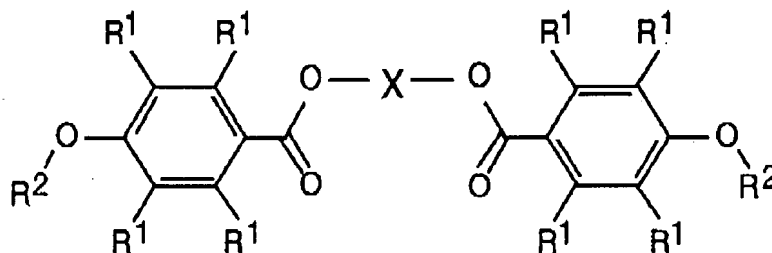
wherein

X is selected from a C₆₋₁₀ aryl group and a C₅₋₁₀ alicyclic group ;

each R¹ is independently selected from hydrogen, halogen, and C₁₋₃ alkyl optionally substituted with halogen, provided that not more than four of the R¹ are C₂ alkyl optionally substituted with halogen, and provided that not more than three of the R¹ are C₃ alkyl optionally substituted with halogen; and

each R² is independently selected from a C₂₋₆ epoxy.

8. (Currently Amended) The compound of claim [1]2, having the formula:



wherein

X is selected from a C₆₋₁₀ aryl group and a C₅₋₁₀ alicyclic group;

each R¹ is independently selected from hydrogen, halogen, and C₁₋₃ alkyl optionally substituted with halogen, provided that not more than four of the R¹ are C₂ alkyl optionally substituted with halogen, and provided that not more than three of the R¹ are C₃ alkyl optionally substituted with halogen;

each R^2 is independently selected from a C_{2-6} epoxy.

9. – 48. (Cancelled)

49. (Previously Presented) The composition of claim 2, wherein the coefficient of thermal expansion of the filler is matched to that of silicon.

50. (Previously Presented) The composition of claim 2, wherein the filler comprises one or more selected from silicon particles, silica particles, sand, quartz, silicon dioxide, and clay.

51. (Previously Presented) The composition of claim 2, wherein a weight percent of the filler in the composition ranges from 50 to 95 wt%.

52. (Previously Presented) The composition of claim 2, wherein the composition comprises an epoxy molding composition.

53. (Previously Presented) The composition of claim 2, further comprising:
a curing agent;
a curing accelerator; and
a curing inhibitor.

54. (New) The composition of claim 2, wherein the filler comprises silicon.